## INTEGRATED CIRCUITS

# DATA SHEET

## 74LVC823A

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

**Product specification** 





## 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

## **FEATURES**

- 5-volt tolerant inputs/outputs, for interfacing with 5-volt logic
- Supply voltage range of 2.7V to 3.6V
- Complies with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 9-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Flow-through pin-out architecture

## **DESCRIPTION**

The 74LVC823A is a high performance, low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-state operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC823A is a 9-bit D-type flip-flop with common clock (CP), Clock Enable ( $\overline{\text{CE}}$ ), Master Reset ( $\overline{\text{MR}}$ ) and 3-State outputs for bus-oriented applications.

The nine flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition provided  $\overline{\text{CE}}$  is LOW. When  $\overline{\text{CE}}$  is HIGH the flip-flops hold their data.

A LOW on MR resets all flip-flops.

When  $\overline{\text{OE}}$  is LOW, the contents of the nine flip-flops is available at the outputs. When  $\overline{\text{OE}}$  is HIGH, the outputs go to the high impedance OFF-state. Operation of the  $\overline{\text{OE}}$  input does not affect the state of the flip-flops.

## **QUICK REFERENCE DATA**

GND = 0 V;  $T_{amb} = 25^{\circ}C$ ;  $t_r = t_f \le 2.5 \text{ ns}$ 

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
. /.	Propagation delay CP to Q <sub>n</sub>	C <sub>L</sub> = 50 pF;	5.1	ns
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay MR to Q <sub>n</sub>	C <sub>L</sub> = 50 pF; V <sub>CC</sub> = 3.3 V	5.2	ns
f <sub>max</sub>	Maximum clock frequency	$C_L = 50 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	150	MHz
C <sub>I</sub>	Input capacitance		5.0	pF
C <sub>PD</sub>	Power dissipation capacitance per flip-flop	Notes 1 and 2	27	pF

### NOTES:

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:

 $f_i$  = input frequency in  $\overline{MHz}$ ;  $C_L$  = output load capacity in pF;

 $f_0$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;

 $\sum (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$ 

2. The condition is  $V_I = GND$  to  $V_{CC}$ 

## **ORDERING INFORMATION**

<u> </u>			
PACKAGES	TEMPERATURE RANGE	ORDERING CODE	PKG. DWG. #
24-Pin Plastic SO	−40°C to +85°C	74LVC823A D	SOT137-1
24-Pin Plastic SSOP Type II	−40°C to +85°C	74LVC823A DB	SOT340-1
24-Pin Plastic TSSOP Type I	−40°C to +85°C	74LVC823A PW	SOT355-1

<sup>1.</sup>  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

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## **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION				
1	ŌĒ	Output enable input (active LOW)				
2, 3, 4, 5, 6, 7, 8, 9, 10	D <sub>0</sub> to D <sub>8</sub>	Data inputs				
11	MR	Master reset (active LOW)				
12	GND	Ground (0 V)				
13	СР	Clock pulse (active rising)				
14	CE	Clock enable (active LOW)				
23, 22, 21, 20, 19, 18, 17, 16, 15	Q <sub>0</sub> to Q <sub>8</sub>	3-State flip-flop outputs				
24	V <sub>CC</sub>	Positive supply voltage				

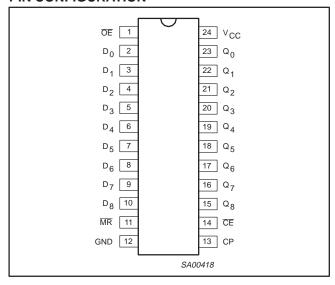
## **FUNCTION TABLE**

ODED ATING MODES			INPUTS			INTERNAL FLID EL ORG	OUTPUTS
OPERATING MODES	ŌĒ	MR	CE	СР	D <sub>n</sub>	INTERNAL FLIP-FLOPS	Q <sub>0</sub> to Q <sub>8</sub>
Clear	L	L	Х	Х	Х	L	L
Load and read register	L L	H H	L L	<b>↑</b>	l h	L H	L H
Load register and disable outputs	H H	H H	L L	X	l h	L H	Z Z
Hold	L	Н	Н	NC	Х	NC	NC

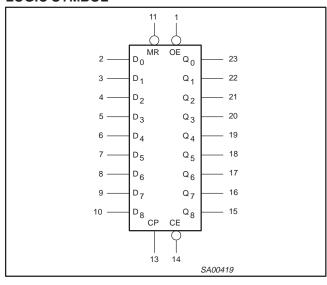
- H = HIGH voltage level
- h = HIGH voltage level one set-up time prior to the LOW-to-HIGH **CP** transition
- = LOW voltage level
- = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition
- Z = high impedance OFF-state
  ↑ = LOW-to-HIGH clock transi
- = LOW-to-HIGH clock transition

NC= no change

## **PIN CONFIGURATION**



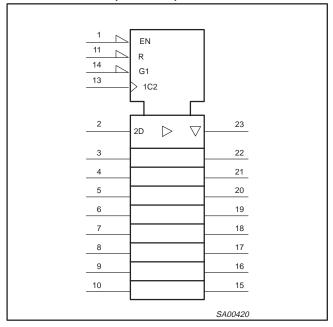
## **LOGIC SYMBOL**



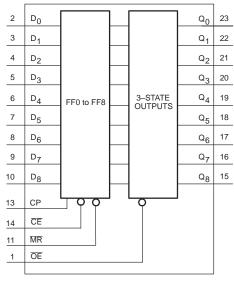
9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

## 74LVC823A

## LOGIC SYMBOL (IEEE/IEC)

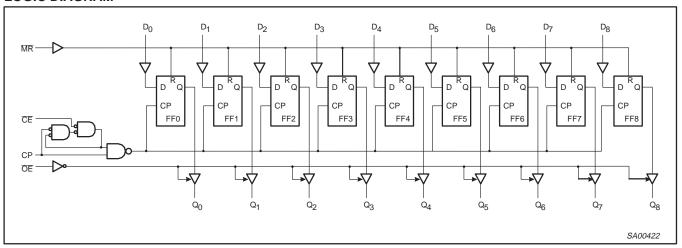


## **FUNCTIONAL DIAGRAM**



SA00421

## **LOGIC DIAGRAM**



## 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	IITS	UNIT
STWIBUL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V	DC supply voltage (for max. speed performance)		2.7	3.6	V
V <sub>CC</sub>	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC Input voltage range		0	5.5	V
Vo	DC output voltage range; output HIGH or LOW state		0	V <sub>CC</sub>	V
	DC output voltage range; output 3-State		0	5.5	
T <sub>amb</sub>	Operating ambient temperature range in free-air		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0	20 10	ns/V

## ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +6.5	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-50	mA
VI	DC input voltage	Note 2	-0.5 to +6.5	V
I <sub>OK</sub>	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
\/	DC output voltage; output HIGH or LOW state	Note 2	-0.5 to V <sub>CC</sub> +0.5	V
Vo	DC output voltage; output 3-State	Note 2	-0.5 to 6.5	V
IO	DC output source or sink current	$V_O = 0$ to $V_{CC}$	±50	mA
I <sub>GND</sub> , I <sub>CC</sub>	DC V <sub>CC</sub> or GND current		±100	mA
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
P <sub>TOT</sub>	Power dissipation per package  – plastic mini-pack (SO)  – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

## NOTES:

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<sup>1.</sup> Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>2.</sup> The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

## DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			L	IMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	40°C to	+85°C	UNIT
			MIN	TYP <sup>1</sup>	MAX	1
.,	LUCI Llevel leget toolte	V <sub>CC</sub> = 1.2V	V <sub>CC</sub>			V
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			1 <sup>v</sup>
V	LOW lavel land to the se	V <sub>CC</sub> = 1.2V			GND	V
$V_{IL}$	LOW level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V			0.8	1 <sup>v</sup>
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -12mA$	V <sub>CC</sub> -0.5			
.,	LUCI I laval autout valtaga	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100 \mu\text{A}$	V <sub>CC</sub> -0.2	V <sub>CC</sub>		
V <sub>OH</sub>	HIGH level output voltage	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -18$ mA	V <sub>CC</sub> -0.6			]
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -24$ mA	V <sub>CC</sub> -0.8			
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 12mA$			0.40	
V <sub>OL</sub>	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$			0.20	V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 24\text{mA}$			0.55	1
l <sub>l</sub>	Input leakage current	$V_{CC} = 3.6V; V_{I} = 5.5V \text{ or GND}$		±0.1	±5	μА
I <sub>OZ</sub>	3-State output OFF-state current	$V_{CC} = 3.6V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $V_O = 5.5V$ or GND		0.1	±5	μА
I <sub>off</sub>	Power off leakage supply	$V_{CC} = 0.0V; V_{I} \text{ or } V_{O} = 5.5V$		0.1	±10	μА
I <sub>CC</sub>	Quiescent supply current	$V_{CC} = 3.6V; V_{I} = V_{CC} \text{ or GND}; I_{O} = 0$		0.1	10	μА
Δl <sub>CC</sub>	Additional quiescent supply current per input pin	$V_{CC} = 2.7 \text{V to } 3.6 \text{V}; V_{I} = V_{CC} -0.6 \text{V}; I_{O} = 0$		5	500	μА

All typical values are at V<sub>CC</sub> = 3.3V and T<sub>amb</sub> = 25°C.
 The specified overdrive current at the data input forces the data input to the opposite logic input state.

# 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

## **AC CHARACTERISTICS**

GND = 0V;  $t_r$  =  $t_f \leq$  2.5ns;  $C_L$  = 50pF;  $R_L$  = 500 $\Omega$ ;  $T_{amb}$  = -40°C to +85°C.

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	V <sub>C</sub>	C = 3.3V ±0	).3V	V <sub>CC</sub> :	= 2.7V	UNIT
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	1
t <sub>PHL</sub> t <sub>PLH</sub>	Propagation delay CP to Q <sub>n</sub>	Figures 1, 4	1.5	5.1	8.0	1.5	8.9	ns
t <sub>PHL</sub>	Propagation delay MR to Q <sub>n</sub>	Figures 1, 4	1.5	5.2	7.9	1.5	8.8	ns
t <sub>PZH</sub> t <sub>PZL</sub>	3-State output enable time  OE to Q <sub>n</sub>	Figures 2, 4	1.5	5.2	7.65	1.5	8.65	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	3-State output disable time  OE to Q <sub>n</sub>	Figures 2, 4	1.5	3.8	6.0	1.5	7.1	ns
t <sub>W</sub>	Clock pulse width HIGH or LOW	Figure 1	3.3			3.3		ns
t <sub>W</sub>	Master Reset pulse width HIGH or LOW	Figure 1	3.3			3.3		ns
t <sub>SU</sub>	Setup time D <sub>n</sub> to CP	Figure 3	1.3			1.8		ns
t <sub>SU</sub>	Setup time CE low before CP	Figure 3	1.8			1.0		ns
t <sub>rem</sub>	Removal time MR	Figure 3	1.0			2.0		ns
t <sub>h</sub>	Hold time HIGH or LOW Dn after CP	Figure 3	2.0			2.0		ns
t <sub>h</sub>	Hold time CE LOW before CP	Figure 3	1.3			1.3		ns
f <sub>max</sub>	Maximum clock pulse frequency	Figure 1	150	200		150		MHz

### NOTE:

<sup>1.</sup> Unless otherwise stated, all typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

## 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

### **AC WAVEFORMS**

 $V_M$  = 1.5V at  $V_{CC} \ge$  2.7V;  $V_M$  = 0.5  $V_{CC}$  at  $V_{CC} <$  2.7V.  $V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

 $V_X$  =  $V_{OL}$  + 0.3V at  $V_{CC}$   $\geq$  2.7V;  $V_X$  =  $V_{OL}$  + 0.1  $V_{CC}$  at  $V_{CC}$  < 2.7V  $V_Y$  =  $V_{OH}$  –0.3V at  $V_{CC}$   $\geq$  2.7V;  $V_Y$  =  $V_{OH}$  – 0.1  $V_{CC}$  at  $V_{CC}$  < 2.7V

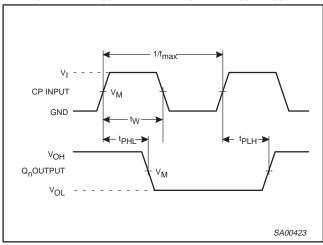


Figure 1. Clock (CP) to output  $(Q_n)$  propagation delays, the clock pulse width and the maximum clock pulse frequency.

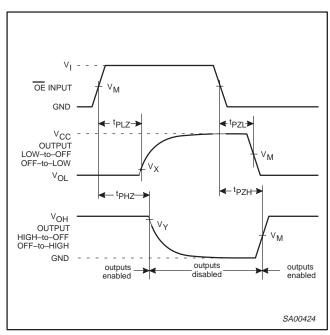


Figure 2. 3-State enable and disable times.

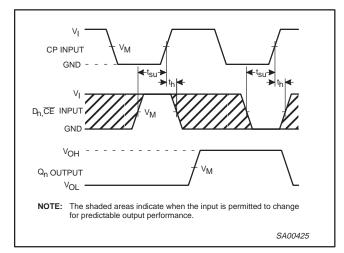


Figure 3. Data setup and hold times for the  $\mathsf{D}_n$  input and  $\overline{\mathsf{CE}}$  input to the CP input.

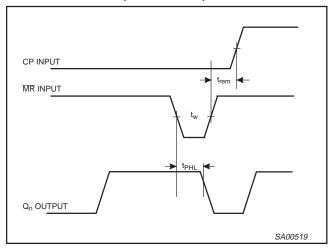


Figure 4. Master reset pulse width, master reset to clock removal time, master reset to output propagation delay.

## **TEST CIRCUIT**

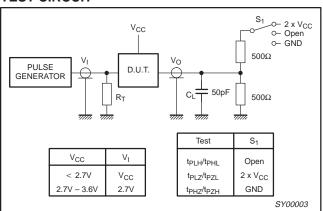


Figure 5. Load circuitry for switching times.

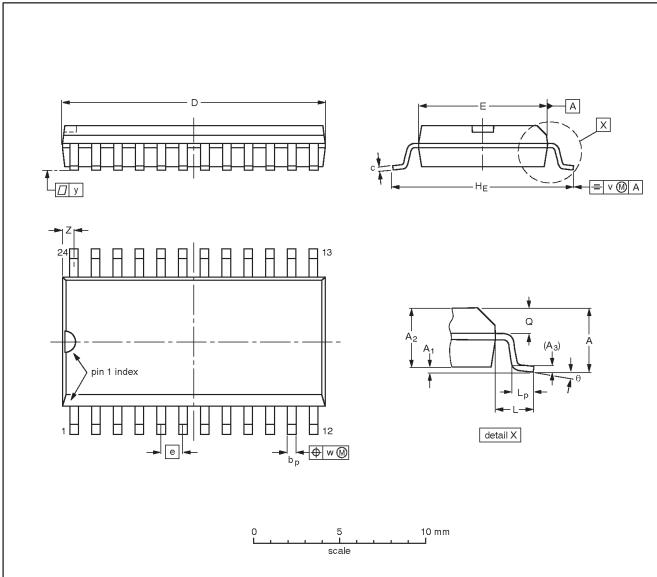
1998 Sep 24 8

## 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

## SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

## Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

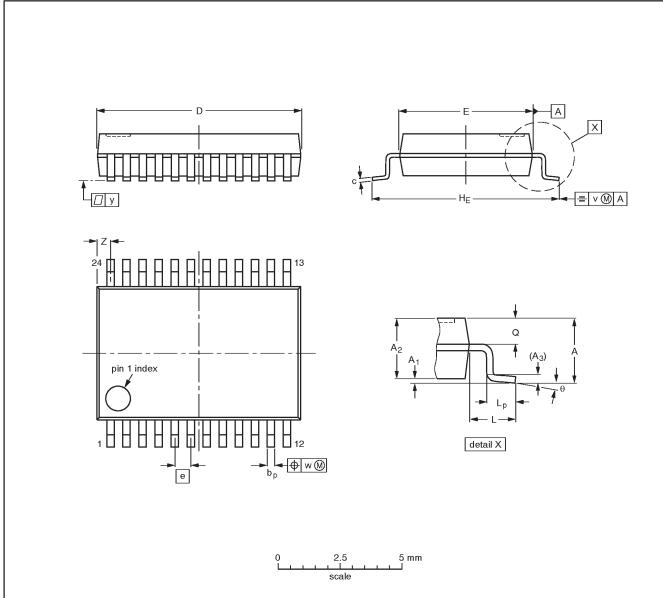
OUTLINE		REFER	RENCES	EUROPEAN	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT137-1	075E05	MS-013AD			<del>-95-01-24</del> 97-05-22

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



## DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Œ	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT340-1		MO-150AG		<b>(</b>	<del>-93-09-08</del> 95-02-04

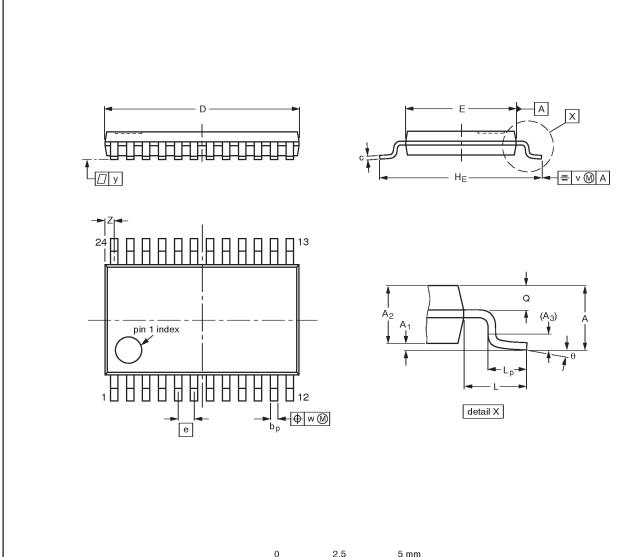
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## 9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



## 0 2.5 5 mm scale

## DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE	
SOT355-1		MO-153AD				<del>93-06-16</del> 95-02-04	

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

### **Definitions**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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